

PHOTOCHEMICALLY AND THERMALLY CURABLE ADHESIVE FORMULATIONS

ABSTRACT OF THE DISCLOSURE

A method for curing a formulation comprising a curable composition by treating the formulation with radiation having a wavelength between about 220 nm and about 600 nm and heating the formulation to generate either acid or base curing agents is provided. A formulation comprising the curable composition, a thermal initiator, and a photoinitiator to generate the acid or base curing agents is also provided. The curable composition may be an epoxy-based composition.